

## **ABSTRACT OF THE DISCLOSURE**

Embodiments of the invention provide methods and apparatuses for efficient and cost-effective imaging of alignment marks. For one embodiment, alignment mark imaging is accomplished separately from, and independent of product imaging through use of a relatively low cost, low resolution, imaging tool. For one embodiment a wafer is exposed to low-resolution light source through a reticle having a number of alignment patterns corresponding to desired alignment marks. For one embodiment, global alignment marks are imaged on a backside of a wafer. Various embodiments of the invention obviate the need for a highly accurate stage and a high-resolution imaging device, and therefore reduce processing costs and processing time.